

SILICON POWER TRANSISTOR

2SD560

NPN SILICON EPITAXIAL TRANSISTOR (DARLINGTON CONNECTION) FOR LOW-FREQUENCY POWER AMPLIFIERS AND LOW-SPEED SWITCHING

The 2SD560 is a mold power transistor developed for low-frequency power amplifiers and low-speed switching. This transistor is ideal for direct driving from the IC output of devices such as pulse motor drivers and relay drivers, and PC terminals.

FEATURES

- C-to-E reverse diode inserted
- Low collector saturation voltage

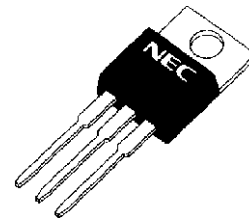
ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Ratings	Unit
Collector to base voltage	V_{CBO}		150	V
Collector to emitter voltage	V_{CEO}		100	V
Emitter to base voltage	V_{EBO}		7.0	V
Collector current (DC)	$I_{C(DC)}$		± 5.0	A
Collector current (pulse)	$I_{C(pulse)}$	$PW \leq 10 \text{ ms}$, duty cycle $\leq 50\%$	± 8.0	A
Base current (DC)	$I_{B(DC)}$		0.5	A
Total power dissipation	P_T	$T_C = 25^\circ\text{C}$	30	W
		$T_A = 25^\circ\text{C}$	1.5	W
Junction temperature	T_j		150	$^\circ\text{C}$
Storage temperature	T_{stg}		$-55 \text{ to } +150$	$^\circ\text{C}$

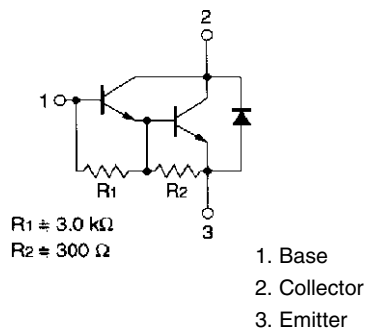
ORDERING INFORMATION

Ordering Name	Package
2SD560	TO-220AB

(TO-220AB)



INTERNAL EQUIVALENT CIRCUIT



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 Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

ELECTRICAL CHARACTERISTICS (T_A = 25°C)

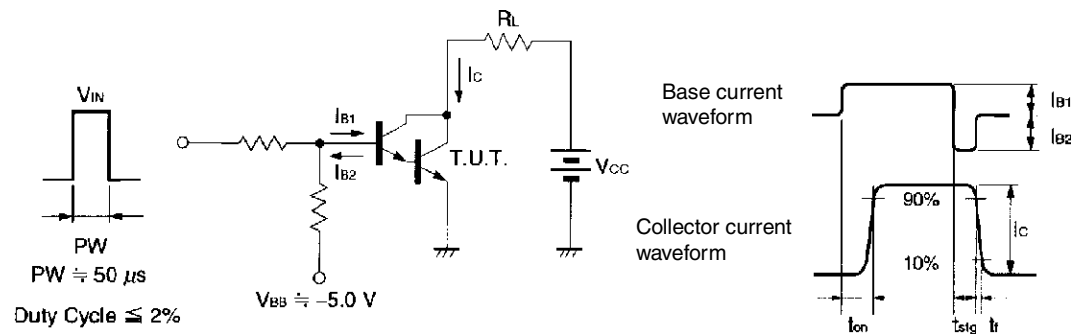
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Collector cutoff current	I _{CBO}	V _{CB} = 100 V, I _E = 0 A			1.0	μA
DC current gain	h _{FE1}	V _{CE} = 2.0 V, I _C = 3.0 A ^{Note}	2,000	6,000	15,000	
	h _{FE2}	V _{CE} = 2.0 V, I _C = 5.0 A ^{Note}	500			
Collector saturation voltage	V _{CE(sat)}	I _C = 3.0 A, I _B = 3.0 mA ^{Note}		0.9	1.5	V
Base saturation voltage	V _{BE(sat)}	I _C = 3.0 A, I _B = 3.0 mA ^{Note}		1.6	2.0	V
Turn-on time	t _{on}	I _C = 3.0 A, R _L = 16.7 Ω, I _{B1} = -I _{B2} = 3.0 mA, V _{CC} ≐ 50 V Refer to the test circuit.		1.0		μs
Storage time	t _{stg}			3.5		μs
Fall time	t _f			1.2		μs

Note Pulse test PW ≤ 350 μs, duty cycle ≤ 2%

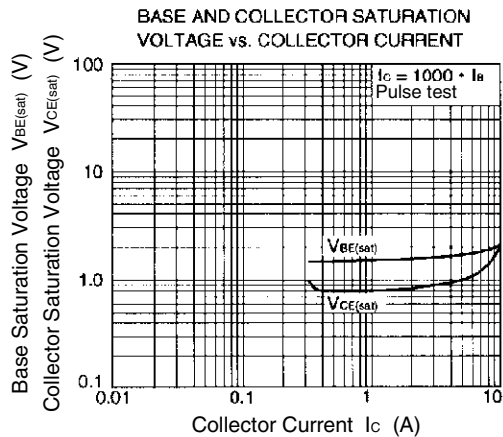
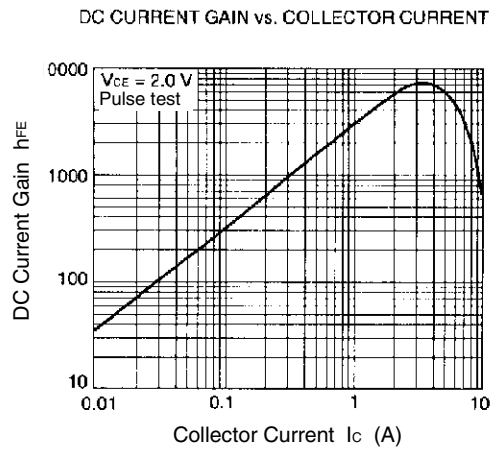
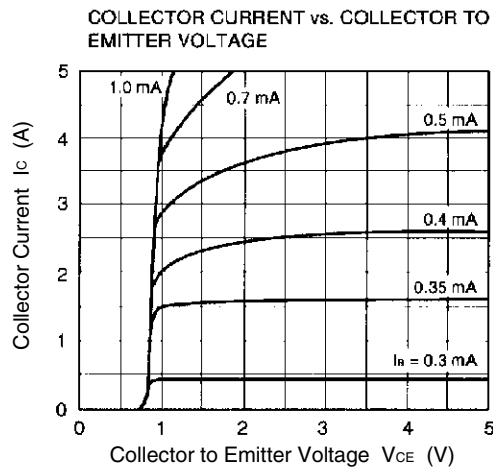
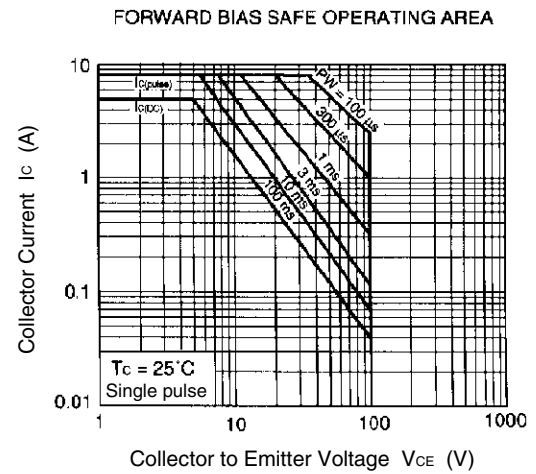
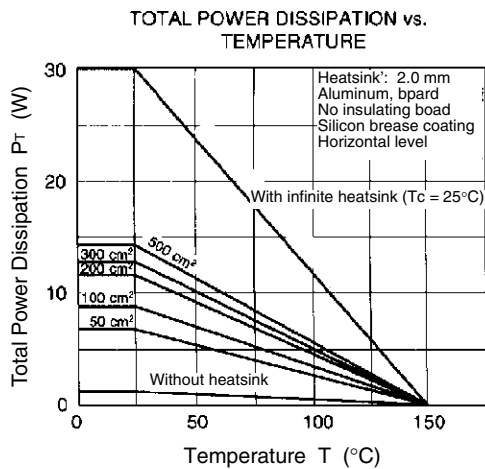
h_{FE} CLASSIFICATION

Marking	MB	LB	KB
h _{FE1}	2,000 to 5,000	3,000 to 7,000	5,000 to 15,000

SWITCHING TIME (t_{on}, t_{stg}, t_f) TEST CIRCUIT

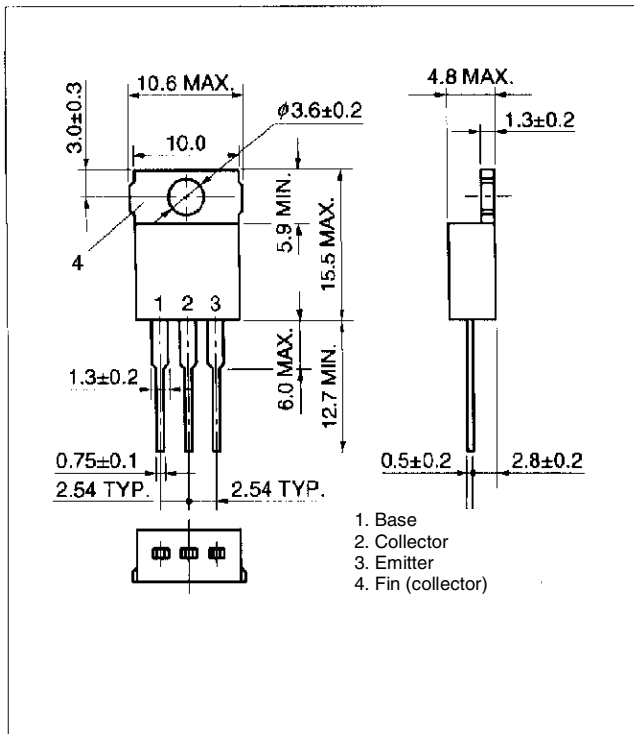


TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)



PACKAGE DRAWING (UNIT: mm)

TO-220AB (MP-25)



[MEMO]

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